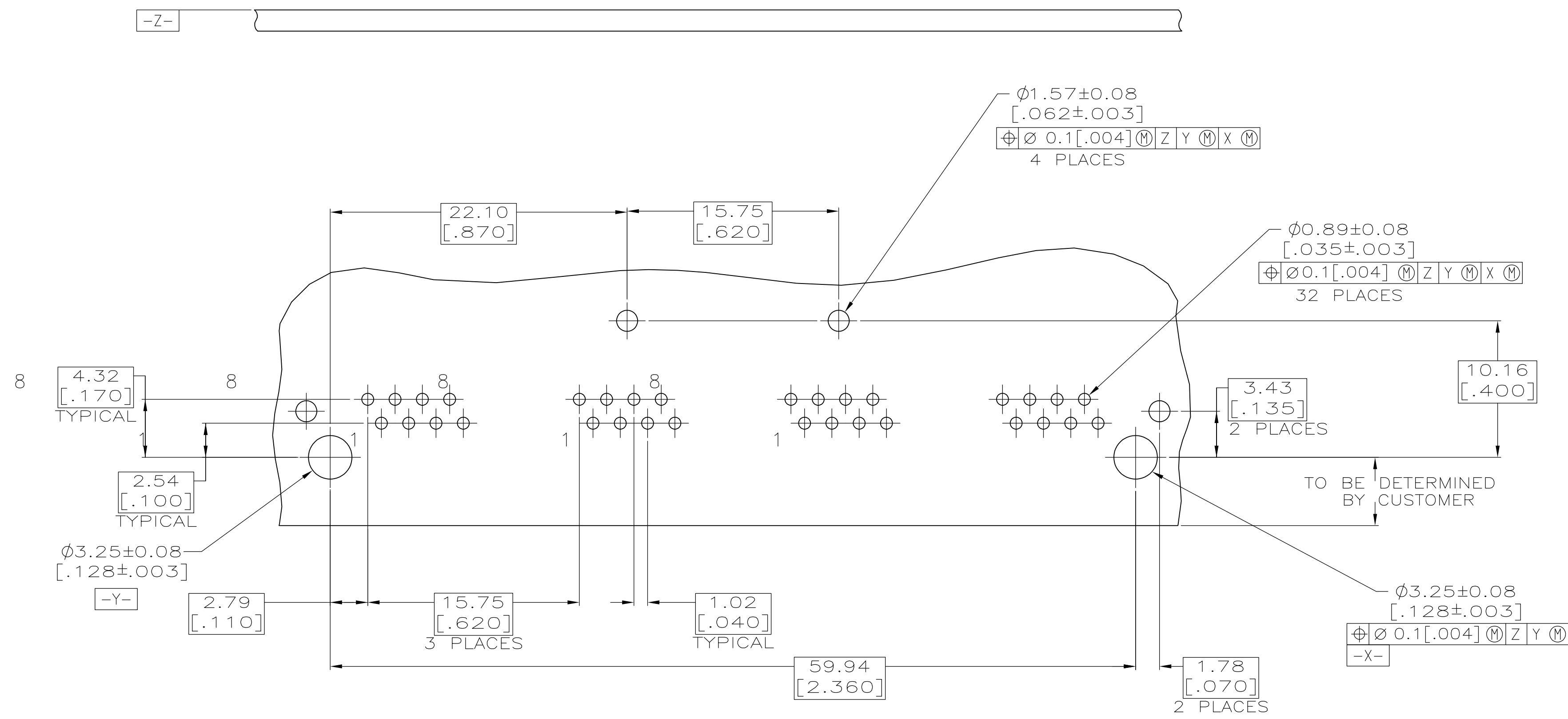
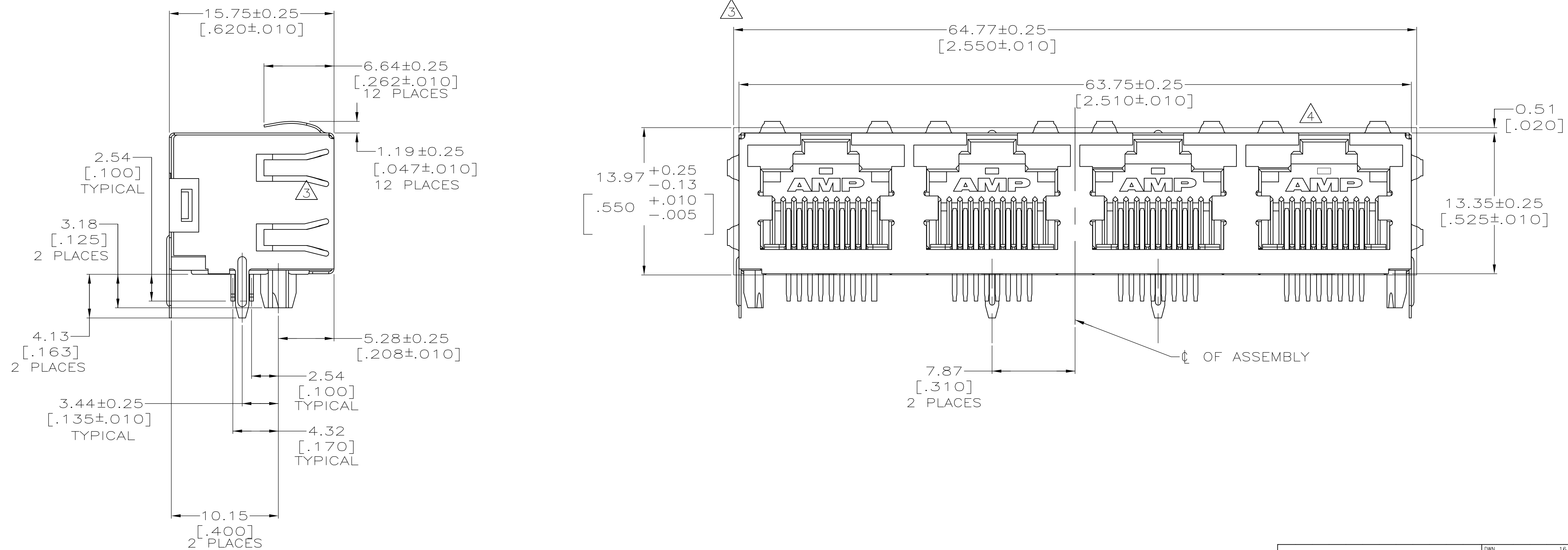


LOC	DIST	REVISIONS				
AA	22	REV	DATE	BY	APPD	
1	PRELIMINARY		29JUN2012	JJ	AC	



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)



- ▲ MATERIAL: POLYESTER LCP
 BLACK, UL94V-0; LEAD FREE IR REFLOW SOLDERING
 PROCESS COMPATIBLE.
- TERMINALS - .36[.014] THICK PHOS BRONZE
 PLATED WITH 3.81µm[.000150] MINIMUM THICK
 MATTE TIN IN SOLDER AREA. 1.27µm [.000050]
 MINIMUM GOLD IN LOCALIZED PLATE
 AREA. ENTIRE TERMINAL PLATED WITH 1.27µm
 [.000050] MINIMUM THICK NICKEL.
 SHIELD - .196[.0077] THICK COPPER ZINC ALLOY
 PREPLATED WITH 2.03µm[.000080] - 3.81µm
 [.000150] BRIGHT TIN OVER 1.27µm
 [.000050] THICK MIN NICKEL.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND
 REGULATIONS PART 68, SUBPART F.
- ▲ SUGGESTED PANEL OPENING DIMENSIONS.
- ▲ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR
 AND TOP PANEL OPENING.

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN	J. ALCORTA - 16JUN2005	TRAY	2170359-1
DIMENSIONS: mm [INCHES]		CHK	J. WESTMAN 16JUN2005	PACKAGE	PART NUMBER
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	S. FLICKINGER 16JUN2005	TE Connectivity	
0 PL	±	NAME	INVERTED MOD JACK ASSEMBLY, 1x4, SHIELDED, PANEL GROUND		
1 PL	±	PRODUCT SPEC	108-1163-4		
2 PL	±	APPLICATION SPEC	114-2154		
3 PL	±	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
4 PL	±	WEIGHT	A1	00779	2170359
ANGLES	±	CUSTOMER DRAWING	SCALE 4:1		SHEET 1 OF 1
MATERIAL	FINISH	REV 1			